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Image Sensors and Imaging Systems 2014

Ralf Widenhorn
Antoine Dupret
Editors

5–6 February 2014
San Francisco, California, United States

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SPIE

Volume 9022

Proceedings of SPIE 0277-786X, v. 9022

Image Sensors and Imaging Systems 2014, edited by Ralf Widenhorn, Antoine Dupret,
Proc. of SPIE-IS&T Electronic Imaging, SPIE Vol. 9022, 902201 · © 2014 SPIE-IS&T
CCC code: 0277-786X/14/$18 · doi: 10.1117/12.2063409

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Please use the following format to cite material from this book:
Author(s), "Title of Paper," in *Image Sensors and Imaging Systems 2014*, edited by Ralf Widenhorn, Antoine Dupret, Proceedings of SPIE-IS&T Electronic Imaging, SPIE Vol. 9022, Article CID Number (2014)

ISSN: 0277-786X
ISBN: 9780819499394

Copublished by
SPIE
P.O. Box 10, Bellingham, Washington 98227-0010 USA
Telephone +1 360 676 3290 (Pacific Time) · Fax +1 360 647 1445
SPIE.org
and
IS&T—The Society for Imaging Science and Technology
7003 Kilworth Lane, Springfield, Virginia, 22151 USA
Telephone +1 703 642 9090 (Eastern Time) · Fax +1 703 642 9094
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Printed in the United States of America.

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